

*SPECIFICATION AMENDMENTS*

Replace the paragraph beginning at page 1, line 8 with:

The present invention relates to a device package, in which an electrode on a device, such as a semiconductor device or optical device, is connected to extra-device wiring or the like on an external wiring substrate through a metal wire, and to a method of manufacturing the device package.

Replace the paragraph beginning at page 1, line 16 with:

In general, an electrode on a semiconductor device or the like is electrically connected through a gold wire to extra-device wiring, such as a wiring pattern on an external wiring substrate ~~by~~, using a wire bonding apparatus (for example, see Japanese Laid-Open Patent Publication No. H05-90320). In such a conventional wire bonding technique, a ball formed at the tip end of the gold wire is ~~firstly first~~ bonded to the electrode on the semiconductor device by applying a load, heat, or ultrasonic ~~wave waves~~. Subsequently, the gold wire is guided by a capillary and moved to a position above the extra device wiring while forming a predetermined bending shape (loop shape) that is arched. Then, the gold wire is landed on the extra device wiring and bonded thereto by the load, heat or ultrasonic ~~wave waves~~ applied by the capillary. Thereafter, the capillary is upwardly withdrawn to ~~thereby~~ complete the wire bonding.

Replace the paragraph beginning at page 5, line 11 with:

Fig. 1 is a perspective view showing a wire bonding apparatus performing the wire bonding by ~~means of~~ the wire bonding technique of the present invention, and an optical device package in which an optical device is electrically connected to an external wiring substrate by the wire bonding apparatus;

Replace the paragraph beginning at page 5, line 20 with:

Figs. 3A to 3C are views showing an operating procedure of the wire bonding using one type of a gold wire; and